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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
08/520,079	08/28/1995	SHUNPEI YAMAZAKI		1321

22204 7590 02/17/2005		**EXAMINER**
NIXON PEABODY, LLP		BROCK II, PAUL E
401 9TH STREET, NW		

ART UNIT	PAPER NUMBER
2815	

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WASHINGTON, DC 20004-2128

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Please find below and/or attached an Office communication concerning this application or proceeding.

PTO-90C (Rev. 10/03)

	Application No.	Applicant(s)
	08/520,079	YAMAZAKI ET AL.
Office Action Summary	Examiner	Art Unit	
	Paul E. Brock II	2815	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE _3_ MONTH(S) FROM
THE MAILING DATE OF THIS COMMUNICATION.
- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed
  after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
  Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any
  earned patent term adjustment. See 37 CFR 1.704(b).

Status

1) ☒ Responsive to communication(s) filed on _24 January 2005_.

2a) ☒ This action is **FINAL**.   2b) ☐ This action is non-final.

3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is
   closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4) ☒ Claim(s) _73-116,123-141 and 143-155_ is/are pending in the application.

   4a) Of the above claim(s) _____ is/are withdrawn from consideration.

5) ☐ Claim(s) _____ is/are allowed.

6) ☒ Claim(s) _73-116,123-141 and 143-155_ is/are rejected.

7) ☐ Claim(s) _____ is/are objected to.

8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9) ☐ The specification is objected to by the Examiner.

10) ☒ The drawing(s) filed on _28 August 1995_ is/are: a) ☒ accepted or b) ☐ objected to by the Examiner.

   Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

   Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).

11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).

   a) ☒ All   b) ☐ Some * c) ☐ None of:

   1. ☒ Certified copies of the priority documents have been received.

   2. ☐ Certified copies of the priority documents have been received in Application No. _____.

   3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage
      application from the International Bureau (PCT Rule 17.2(a)).

   * See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) ☐ Notice of References Cited (PTO-892)
2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
3) ☒ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
   Paper No(s)/Mail Date 8-18-04

4) ☐ Interview Summary (PTO-413)
   Paper No(s)/Mail Date. _____ .
5) ☐ Notice of Informal Patent Application (PTO-152)
6) ☐ Other: _____.

DETAILED ACTION

Information Disclosure Statement

1.   Reference US-6,616,613 cited on the information disclosure statement filed August 18

2004 is a Patent to Goodman entitled "Physiological signal monitoring system" patented on

September 9, 2003. This is believed to be an incorrect citation as the information disclosure

statement credits Yamazaki et al. with this patent with a patent date of September 2, 2003. U.S.

Patent 6,613,613 to Yamazaki on September 2, 2003 has been considered on the attached PTO-

892.

Claim Rejections - 35 USC § 103

2.   The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all

obviousness rejections set forth in this Office action:

> (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in
> section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are
> such that the subject matter as a whole would have been obvious at the time the invention was made to a person
> having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the
> manner in which the invention was made.

3.   Claims 73 – 116, 123 –141, and 143 – 155 are rejected under 35 U.S.C. 103(a) as being

unpatentable over Zhang et al. (USPAT 5563426, Zhang[1]).

With regard to claim 73, Zhang[1] discloses in figure 4c a thin film transistor. Zhang[1]

discloses in figures 1a – 1c, 2a - 2d, and 4a – 4c a crystalline semiconductor island (3) over a

substrate (1a) having an insulating surface (1b). Zhang[1] discloses in figures 4b and 4c source

(25a and 25c) and drain regions (25b and 25d) in said semiconductor island. Zhang[1] discloses in

figure 4b a channel forming region (between 25a and 25b in figure 4b) between said source and drain regions. Zhang[1] discloses in figures 4a – 4c a gate insulating film (22) adjacent to at least said channel forming region. Zhang[1] discloses in figures 1a- 1c, 2a – 2d, and 4a – 4c a gate electrode (23a) adjacent to said channel forming region having said gate insulating film therebetween, wherein said channel forming region has no grain boundary (4). No differences have been pointed out in the formation of the channel forming region of Zhang[1] and the channel forming region of the current pending claim in view of the currently pending specification. Therefore Zhang[1] must teach in figures 1a – 1c, 2a – 2d and 4a – 4c wherein said semiconductor island includes a spin density not higher than 1×10^{17} cm^{-3}, because an identical spin density is a property that must be shared by products that result from two processes that are the same. Zhang[1] discloses in figures 4c and column 11, lines 47 – 56 wherein said crystalline semiconductor island includes hydrogen at concentration less than 1×10^{20} cm^{-3} (i.e. the known atomic density of Si is 10^{22} cm^{-3}, less than 5% of 10^{22} is less than 10^{20}). It is not clear if Zhang[1] teaches that the hydrogen concentration is not greater than 1×10^{20} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use the hydrogen atom concentration of not greater than 1×10^{20} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap. Further, any changes in particular device concentrations or properties would have been routine experimentation for one of ordinary skill seeking to maximize device function in the device of Zhang[1].

With regard to claim 74, Zhang[1] discloses in figures 1a, 1b, and 2a; and column 6, lines 19 – 40 wherein the crystalline semiconductor island comprise a material of Ni.

With regard to claim 75, Zhang[1] discloses in figures 1a, 1b, and 2a; and column 6, lines 19 – 40 a thin film transistor wherein said material is included in said semiconductor island at a concentration less than 5×10^{19} cm^{-3}. It is not clear if Zhang[1] teaches that the material is included in the semiconductor at a concentration not greater than 5×10^{19} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use the material included in the semiconductor at a concentration not greater than 5×10^{19} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 76, Zhang[1] discloses in column 9, lines 38 – 45 a thin film transistor wherein said semiconductor island includes the point defect (oxygen) of less 1×10^{18} cm^{-3}. It is not clear if Zhang[1] teaches wherein said semiconductor island includes a point defect of 1×10^{16} cm^{-3} or more. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to have said semiconductor island include a point defect of 1×10^{16} cm^{-3} or more in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap. Zhang[1] teaches in column 11, lines 47 – 56 that is obvious to have the hydrogen element for neutralizing the point defect at a concentration of 1×10^{18}.

With regard to claim 77, it is obvious in Zhang[1] wherein said semiconductor island includes the spin density not lower than 1×10^{15} cm^{-3}.

With regard to claim 78, Zhang[1] discloses in column 4, lines 18 – 20 wherein said semiconductor island is a silicon island.

With regard to claim 79, Zhang[1] discloses in column 9, lines 38 – 43 wherein the crystalline semiconductor island includes carbon and nitrogen at a concentration less than $1 \times$

10^{18} cm^{-3}, and oxygen at a concentration less than 1 x 10^{18} cm^{-3}. It is not clear if Zhang[1] teaches

that said crystalline semiconductor island includes carbon and nitrogen at a concentration not

lower than 1 x 10^{16} cm^{-3}, and oxygen at a concentration not lower than 1 x 10^{17} cm^{-3}. MPEP

2144.05 states that overlapping ranges are obvious. It would have been obvious to one of

ordinary skill in the art to use carbon and nitrogen at a concentration not lower than 1 x 10^{16} cm^{-3}

^{3}, and oxygen at a concentration not lower than 1 x 10^{17} cm^{-3} in the device of Zhang[1] because the

current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 80, Zhang[1] discloses in figure 4c a thin film transistor. Zhang[1]

discloses in figures 1a – 1c, 2a - 2d, and 4a – 4c a crystalline semiconductor island on an

insulating surface. Zhang[1] discloses in figures 4b and 4c source and drain regions in said

semiconductor island. Zhang[1] discloses in figure 4b a channel forming region between said

source and drain regions. Zhang[1] discloses in figures 4a – 4c a gate insulating film on at least

said channel forming region. Zhang[1] discloses in figures 1a- 1c, 2a – 2d, and 4a – 4c a gate

electrode over said channel forming region having said gate insulating film therebetween,

wherein said channel forming region has no grain boundary. Zhang[1] discloses in column 9, lines

38 – 45 a thin film transistor wherein said semiconductor island includes the point defect

(oxygen) of less 1 x 10^{18} cm^{-3}. It is not clear if Zhang[1] teaches wherein said semiconductor island

includes a point defect of 1 x 10^{16} cm^{-3} or more. MPEP 2144.05 states that overlapping ranges

are obvious. It would have been obvious to one of ordinary skill in the art to have said

semiconductor island include a point defect of 1 x 10^{16} cm^{-3} or more in the device of Zhang[1]

because the current claimed range and the disclosed range in Zhang[1] overlap. Zhang[1] discloses in

figures 4c and column 11, lines 47 – 56 wherein said crystalline semiconductor island includes

hydrogen at concentration less than 1×10^{20} cm^{-3} (i.e. the known atomic density of Si is 10^{22} cm^{-3},

less than 5% of 10^{22} is less than 10^{20}). It is not clear if Zhang[1] teaches that the hydrogen

concentration is not higher than 1×10^{20} cm^{-3}. MPEP 2144.05 states that overlapping ranges are

obvious. It would have been obvious to one of ordinary skill in the art to use the hydrogen atom

concentration of not higher than 1×10^{20} cm^{-3} in the device of Zhang[1] because the current

claimed range and the disclosed range in Zhang[1] overlap. Further, any changes in particular

device concentrations or properties would have been routine experimentation for one of ordinary

skill seeking to maximize device function in the device of Zhang[1].

With regard to claim 81, Zhang[1] discloses in figures 1a, 1b, and 2a; and column 6, lines

19 – 40 wherein the crystalline semiconductor island comprise a material of Ni.

With regard to claim 82, Zhang[1] discloses in figures 1a, 1b, and 2a; and column 6, lines

19 – 40 a thin film transistor wherein said material is included in said semiconductor island at a

concentration less than 5×10^{19} cm^{-3}. It is not clear if Zhang[1] teaches that the material is included

in the semiconductor at a concentration not higher than 5×10^{19} cm^{-3}. MPEP 2144.05 states that

overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to

use the material included in the semiconductor at a concentration not higher than 5×10^{19} cm^{-3}in

the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1]

overlap.

With regard to claim 83, Zhang[1] discloses in figures 4c and column11, lines 47 – 56

wherein said semiconductor island includes hydrogen for neutralizing the point defect at a

concentration less than 1×10^{20} cm^{-3}. It is not clear if Zhang[1] teaches that the hydrogen

concentration is not lower than 1×10^{-15} cm^{-3}. MPEP 2144.05 states that overlapping ranges are

obvious. It would have been obvious to one of ordinary skill in the art to use the hydrogen atom

concentration of not lower than 1 x 10^{-15} cm^{-3} in the device of Zhang[1] because the current

claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 84, No differences have been pointed out in the formation of the

channel forming region of Zhang[1] and the channel forming region of the current pending claim

in view of the currently pending specification. Therefore Zhang[1] must teach in figures 1a – 1c,

2a – 2d and 4a – 4c wherein said semiconductor island includes a spin density of 1 x 10^{15} to 1 x

10^{17} cm^{-3}, because an identical spin density is a property that must be shared by products that

result from two processes that are the same.

With regard to claim 85, Zhang[1] discloses in column 4, lines 18 – 20 wherein said

semiconductor island is a silicon island.

With regard to claim 86, Zhang[1] discloses in column 9, lines 38 – 43 wherein the

crystalline semiconductor island includes carbon and nitrogen at a concentration less than 1 x

10^{18} cm^{-3}, and oxygen at a concentration less than 1 x 10^{18} cm^{-3}. It is not clear if Zhang[1] teaches

that said crystalline semiconductor island includes carbon and nitrogen at a concentration not

lower than 1 x 10^{16} cm^{-3}, and oxygen at a concentration not lower than 1 x 10^{17} cm^{-3}. MPEP

2144.05 states that overlapping ranges are obvious. It would have been obvious to one of

ordinary skill in the art to use carbon and nitrogen at a concentration not lower than 1 x 10^{16} cm^{-}

^{3}, and oxygen at a concentration not lower than 1 x 10^{17} cm^{-3} in the device of Zhang[1] because the

current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 87, Zhang[1] discloses in figure 4c a semiconductor device. Zhang[1]

discloses in figures 1a – 1c, 2a - 2d, and 4a – 4c a crystalline semiconductor island on an

insulating surface. Zhang[1] discloses in figures 4b and 4c source and drain regions in said

semiconductor island. Zhang[1] discloses in figure 4b a channel forming region between said

source and drain regions. Zhang[1] discloses in figures 1a- 1c, 2a – 2d, and 4a – 4c a gate

insulating film adjacent to at least said channel forming region. Zhang[1] discloses in figures 1a-

1c, 2a – 2d, and 4a – 4c a gate electrode adjacent to said channel forming region having said gate

insulating film therebetween, wherein said crystalline semiconductor island is formed in a

monodomain region which contains no grain boundary. Zhang[1] discloses in figures 4c and

column11, lines 47 – 56 wherein said crystalline semiconductor island includes hydrogen at

concentration less than 1×10^{20} cm^{-3} (i.e. the known atomic density of Si is 10^{22} cm^{-3}, less than

5% of 10^{22} is less than 10^{20}). It is not clear if Zhang[1] teaches that the hydrogen concentration is

not higher than 1×10^{20} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It

would have been obvious to one of ordinary skill in the art to use the hydrogen atom

concentration of not higher than 1×10^{20} cm^{-3} in the device of Zhang[1] because the current

claimed range and the disclosed range in Zhang[1] overlap. Zhang[1] discloses in column 9, lines 38

– 45 wherein the semiconductor device includes a p-channel thin film transistor having a

mobility in a range of 20 – 100 cm^2/Vs. Zhang[1] is silent to the fact that the semiconductor

device includes a p-channel thin film transistor having mobility in a range of 200-400 cm^2/Vs.

Mobility is a function of the purity of the single crystal (monodomain) semiconductor. MPEP

section 2144.04, VII teaches that it is obvious to one of ordinary skill in the art to have a more

purely defect free p-channel monodomain region with mobility in a range of 200-400 cm^2/Vs in

the device of Zhang[1]. This is because the prior art teaches a suitable method for obtaining the

claimed mobility, and that fact that the monodomain region of Zhang[1] has the same utility as that

of the claimed invention. Further, any changes in particular device concentrations or properties would have been routine experimentation for one of ordinary skill seeking to maximize device function in the device of Zhang[1].

With regard to claim 88, Zhang[1] discloses in figures 1a, 1b, and 2a; and column 6, lines 19 – 40 wherein said crystalline semiconductor island comprises a material Ni.

With regard to claim 89, Zhang[1] discloses in figures 1a, 1b, and 2a; and column 6, lines 19 – 40 a thin film transistor wherein said material is included in said semiconductor island at a concentration less than 5×10^{19} cm^{-3}. It is not clear if Zhang[1] teaches that the material is included in the semiconductor at a concentration not higher than 5×10^{19} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use the material included in the semiconductor at a concentration not higher than 5×10^{19} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 90, Zhang[1] discloses in column 4, lines 18 – 20 wherein said semiconductor island is a silicon island.

With regard to claim 91, Zhang[1] discloses in column 9, lines 38 – 43 wherein the crystalline semiconductor island includes carbon and nitrogen at a concentration less than 1×10^{18} cm^{-3}, and oxygen at a concentration less than 1×10^{18} cm^{-3}. It is not clear if Zhang[1] teaches that said crystalline semiconductor island includes carbon and nitrogen at a concentration not lower than 1×10^{16} cm^{-3}, and oxygen at a concentration not lower than 1×10^{17} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use carbon and nitrogen at a concentration not lower than 1×10^{16} cm

[3], and oxygen at a concentration not lower than 1 x 10^{17} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 92, Zhang[1] teaches in figures 1a, 1b, 2a – 2d; and column 12, lines 1 – 30 wherein said monodomain region has a grain size of 50 μm or more. It should be noted that the crystal grains (3) grown around metal portions (2) must have a grain size of 50 – 100 μm when the metal portions are set from 25 – 50 μm apart as disclosed by Zhang[1] in column 12, lines 1 – 30.

With regard to claim 93, Zhang[1] discloses in figure 4c semiconductor device. Zhang[1] discloses in figures 1a – 1c, 2a - 2d, and 4a – 4c a crystalline semiconductor island on an insulating surface. Zhang[1] discloses in figures 4b and 4c source and drain regions in said semiconductor island. Zhang[1] discloses in figure 4b a channel forming region between said source and drain regions. Zhang[1] discloses in figures 1a- 1c, 2a – 2d, and 4a – 4c a gate insulating film adjacent to at least said channel forming region. Zhang[1] discloses in figures 1a-1c, 2a – 2d, and 4a – 4c a gate electrode adjacent to said channel forming region having said gate insulating film therebetween, wherein said channel forming region is formed in a monodomain region which contains no grain boundary. Zhang[1] discloses in figures 4c and column 11, lines 47 – 56 wherein said crystalline semiconductor island includes hydrogen at concentration less than 1 x 10^{20} cm^{-3} (i.e. the known atomic density of Si is 10^{22} cm^{-3}, less than 5% of 10^{22} is less than 10^{20}). It is not clear if Zhang[1] teaches that the hydrogen concentration is not higher than 1 x 10^{20} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use the hydrogen atom concentration of not higher than 1 x 10^{20} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1]

overlap. Zhang[1] discloses in column 9, lines 38 – 45 wherein the semiconductor device includes

a n-channel thin film transistor having a mobility in a range of 30 – 150 cm^2/Vs. Zhang[1] is silent

to the fact that the semiconductor device includes an n-channel thin film transistor having

mobility in a range of 500-1000 cm^2/Vs. Mobility is a function of the purity of the single crystal

(monodomain) semiconductor. MPEP section 2144.04, VII teaches that it is obvious to one of

ordinary skill in the art to have a more purely defect free n-channel monodomain region with

mobility in a range of 500-1000 cm^2/Vs in the device of Zhang[1]. This is because the prior art

teaches a suitable method for obtaining the claimed mobility, and that fact that the monodomain

region of Zhang[1] has the same utility as that of the claimed invention. Further, any changes in

particular device concentrations or properties would have been routine experimentation for one

of ordinary skill seeking to maximize device function in the device of Zhang[1].

With regard to claim 94, Zhang[1] discloses in figures 1a, 1b, and 2a; and column 6, lines

19 – 40 wherein said crystalline semiconductor island comprises a material Ni.

With regard to claim 95, Zhang[1] discloses in figures 1a, 1b, and 2a; and column 6, lines

19 – 40 a thin film transistor wherein said material is included in said semiconductor island at a

concentration less than 5 x 10^{19} cm^{-3}. It is not clear if Zhang[1] teaches that the material is included

in the semiconductor at a concentration not higher than 5 x 10^{19} cm^{-3}. MPEP 2144.05 states that

overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to

use the material included in the semiconductor at a concentration not higher than 5 x 10^{19} cm^{-3} in

the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1]

overlap.

With regard to claim 96, Zhang[1] discloses in column 4, lines 18 – 20 wherein said semiconductor island is a silicon island.

With regard to claim 97, Zhang[1] discloses in column 9, lines 38 – 43 wherein the crystalline semiconductor island includes carbon and nitrogen at a concentration less than 1 x 10^{18} cm^{-3}, and oxygen at a concentration less than 1 x 10^{18} cm^{-3}. It is not clear if Zhang[1] teaches that said crystalline semiconductor island includes carbon and nitrogen at a concentration not lower than 1 x 10^{16} cm^{-3}, and oxygen at a concentration not lower than 1 x 10^{17} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use carbon and nitrogen at a concentration not lower than 1 x 10^{16} cm^{-3}, and oxygen at a concentration not lower than 1 x 10^{17} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 98, Zhang[1] teaches in figures 1a, 1b, 2a – 2d; and column 12, lines 1 – 30 wherein said monodomain region has a grain size of 50 μm or more. It should be noted that the crystal grains (3) grown around metal portions (2) must have a grain size of 50 – 100 μm when the metal portions are set from 25 – 50 μm apart as disclosed by Zhang[1] in column 12, lines 1 – 30.

With regard to claim 99, Zhang[1] discloses in figure 4c semiconductor device. Zhang[1] discloses in column 9, lines 38 – 45 a p-channel thin film transistor. Zhang[1] discloses in column 9, lines 38 – 45 an n-channel thin film transistor. Zhang[1] discloses in figures 1a – 1c, 2a - 2d, and 4a – 4c a crystalline semiconductor island on an insulating surface. Zhang[1] discloses in figures 4b and 4c source and drain regions in said semiconductor island. Zhang[1] discloses in figure 4b a channel forming region between said source and drain regions. Zhang[1] discloses in figures 1a-

1c, 2a – 2d, and 4a – 4c a gate insulating film adjacent to at least said channel forming region.

Zhang[1] discloses in figures 1a- 1c, 2a – 2d, and 4a – 4c a gate electrode adjacent to said channel

forming region having said gate insulating film therebetween, wherein said crystalline

semiconductor island is formed in a monodomain region which contains no grain boundary.

Zhang[1] discloses in figures 4c and column11, lines 47 – 56 wherein said crystalline

semiconductor island includes hydrogen at concentration less than 1×10^{20} cm^{-3} (i.e. the known

atomic density of Si is 10^{22} cm^{-3}, less than 5% of 10^{22} is less than 10^{20}). It is not clear if Zhang[1]

teaches that the hydrogen concentration is not higher than 1×10^{20} cm^{-3}. MPEP 2144.05 states

that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the

art to use the hydrogen atom concentration of not higher than 1×10^{20} cm^{-3} in the device of

Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap. Further,

any changes in particular device concentrations or properties would have been routine

experimentation for one of ordinary skill seeking to maximize device function in the device of

Zhang[1].

With regard to claim 100, Zhang[1] discloses in figures 1a, 1b, and 2a; and column 6, lines

19 – 40 wherein said crystalline semiconductor island comprises a material Ni.

With regard to claim 101, Zhang[1] discloses in figures 1a, 1b, and 2a; and column 6, lines

19 – 40 a thin film transistor wherein said material is included in said semiconductor island at a

concentration less than 5×10^{19} cm^{-3}. It is not clear if Zhang[1] teaches that the material is included

in the semiconductor at a concentration not higher than 5×10^{19} cm^{-3}. MPEP 2144.05 states that

overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to

use the material included in the semiconductor at a concentration not higher than 5×10^{19} cm^{-3} in

the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1]

overlap.

With regard to claim 102, Zhang[1] discloses in column 4, lines 18 – 20 wherein said

semiconductor island is a silicon island.

With regard to claim 103, Zhang[1] discloses in column 9, lines 38 – 43 wherein the

crystalline semiconductor island includes carbon and nitrogen at a concentration less than $1 \times$

10^{18} cm^{-3}, and oxygen at a concentration less than 1×10^{18} cm^{-3}. It is not clear if Zhang[1] teaches

that said crystalline semiconductor island includes carbon and nitrogen at a concentration not

lower than 1×10^{16} cm^{-3}, and oxygen at a concentration not lower than 1×10^{17} cm^{-3}. MPEP

2144.05 states that overlapping ranges are obvious. It would have been obvious to one of

ordinary skill in the art to use carbon and nitrogen at a concentration not lower than 1×10^{16} cm^{-}

^{3}, and oxygen at a concentration not lower than 1×10^{17} cm^{-3} in the device of Zhang[1] because the

current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 104, Zhang[1] teaches in figures 1a, 1b, 2a – 2d; and column 12, lines

1 – 30 wherein said monodomain region has a grain size of 50 μm or more. It should be noted

that the crystal grains (3) grown around metal portions (2) must have a grain size of 50 – 100 μm

when the metal portions are set from 25 – 50 μm apart as disclosed by Zhang[1] in column 12,

lines 1 – 30.

With regard to claim 105, Zhang[1] discloses in figure 4c semiconductor device. Zhang[1]

discloses in column 9, lines 38 – 45 a p-channel thin film transistor. Zhang[1] discloses in column

9, lines 38 – 45 an n-channel thin film transistor. Zhang[1] discloses in figures 1a – 1c, 2a - 2d, and

4a – 4c a crystalline semiconductor island on an insulating surface. Zhang[1] discloses in figures

4b and 4c source and drain regions in said semiconductor island. Zhang[1] discloses in figure 4b a channel forming region between said source and drain regions. Zhang[1] discloses in figures 1a-1c, 2a – 2d, and 4a – 4c a gate insulating film adjacent to at least said channel forming region. Zhang[1] discloses in figures 1a- 1c, 2a – 2d, and 4a – 4c a gate electrode adjacent to said channel forming region having said gate insulating film therebetween, wherein said channel forming region is formed in a monodomain region which contains no grain boundary. Zhang[1] discloses in column 9, lines 38 – 43 wherein the crystalline semiconductor island includes carbon at a concentration less than 1×10^{18} cm^{-3}. It is not clear if Zhang[1] teaches that said crystalline semiconductor island includes carbon at a concentration not higher than 5×10^{18} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use carbon at a concentration not higher than 5×10^{18} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap. Zhang[1] discloses in figures 4c and column 11, lines 47 – 56 wherein said crystalline semiconductor island includes hydrogen at concentration less than 1×10^{20} cm^{-3} (i.e. the known atomic density of Si is 10^{22} cm^{-3}, less than 5% of 10^{22} is less than 10^{20}). It is not clear if Zhang[1] teaches that the hydrogen concentration is not higher than 1×10^{20} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use the hydrogen atom concentration of not higher than 1×10^{20} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap. Further, any changes in particular device concentrations or properties would have been routine experimentation for one of ordinary skill seeking to maximize device function in the device of Zhang[1].

With regard to claim 106, Zhang[1] discloses in figures 1a, 1b, and 2a; and column 6, lines 19 – 40 wherein said crystalline semiconductor island comprises a material Ni.

With regard to claim 107, Zhang[1] discloses in figures 1a, 1b, and 2a; and column 6, lines 19 – 40 a thin film transistor wherein said material is included in said semiconductor island at a concentration less than 5×10^{19} cm^{-3}. It is not clear if Zhang[1] teaches that the material is included in the semiconductor at a concentration not higher than 5×10^{19} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use the material included in the semiconductor at a concentration not higher than 5×10^{19} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 108, Zhang[1] discloses in column 4, lines 18 – 20 wherein said semiconductor island is a silicon island.

With regard to claim 109, Zhang[1] discloses in column 9, lines 38 – 43 wherein the crystalline semiconductor island includes carbon and nitrogen at a concentration less than 1×10^{18} cm^{-3}, and oxygen at a concentration less than 1×10^{18} cm^{-3}. It is not clear if Zhang[1] teaches that said crystalline semiconductor island includes carbon and nitrogen at a concentration not lower than 1×10^{16} cm^{-3}, and oxygen at a concentration not lower than 1×10^{17} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use carbon and nitrogen at a concentration not lower than 1×10^{16} cm^{-3}, and oxygen at a concentration not lower than 1×10^{17} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 110, Zhang[1] teaches in figures 1a, 1b, 2a – 2d; and column 12, lines 1 – 30 wherein said monodomain region has a grain size of 50 μm or more. It should be noted that the crystal grains (3) grown around metal portions (2) must have a grain size of 50 – 100 μm when the metal portions are set from 25 – 50 μm apart as disclosed by Zhang[1] in column 12, lines 1 – 30.

With regard to claim 111, Zhang[1] discloses in figure 4c semiconductor device. Zhang[1] discloses in figures 8a and 8b; and column 9, lines 28 - 37 an active matrix circuit portion including at least a first thin film transistor. Zhang[1] discloses in column 9, lines 38 – 45 a driving circuit portion including at least a second thin film transistor. Zhang[1] discloses in figures 1a – 1c, 2a - 2d, and 4a – 4c a crystalline semiconductor island on an insulating surface. Zhang[1] discloses in figures 4b and 4c source and drain regions in said semiconductor island. Zhang[1] discloses in figure 4b a channel forming region between said source and drain regions. Zhang[1] discloses in figures 1a- 1c, 2a – 2d, and 4a – 4c a gate insulating film adjacent to at least said channel forming region. Zhang[1] discloses in figures 1a- 1c, 2a – 2d, and 4a – 4c a gate electrode adjacent to said channel forming region having said gate insulating film therebetween, wherein said crystalline semiconductor island is formed in a monodomain region which contains no grain boundary. Zhang[1] discloses in figures 4c and column11, lines 47 – 56 wherein said crystalline semiconductor island includes hydrogen at concentration less than 1×10^{20} cm^{-3} (i.e. the known atomic density of Si is 10^{22} cm^{-3}, less than 5% of 10^{22} is less than 10^{20}). It is not clear if Zhang[1] teaches that the hydrogen concentration is not higher than 1×10^{20} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use the hydrogen atom concentration of not higher than 1×10^{20} cm^{-3} in the device of

Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap. Further, any changes in particular device concentrations or properties would have been routine experimentation for one of ordinary skill seeking to maximize device function in the device of Zhang[1].

With regard to claim 112, Zhang[1] discloses in figures 1a, 1b, and 2a; and column 6, lines 19 – 40 wherein said crystalline semiconductor island comprises a material Ni.

With regard to claim 113, Zhang[1] discloses in figures 1a, 1b, and 2a; and column 6, lines 19 – 40 a thin film transistor wherein said material is included in said semiconductor island at a concentration less than 5×10^{19} cm^{-3}. It is not clear if Zhang[1] teaches that the material is included in the semiconductor at a concentration not higher than 5×10^{19} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use the material included in the semiconductor at a concentration not higher than 5×10^{19} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 114, Zhang[1] discloses in column 4, lines 18 – 20 wherein said semiconductor island is a silicon island.

With regard to claim 115, Zhang[1] discloses in column 9, lines 38 – 43 wherein the crystalline semiconductor island includes carbon and nitrogen at a concentration less than 1×10^{18} cm^{-3}, and oxygen at a concentration less than 1×10^{18} cm^{-3}. It is not clear if Zhang[1] teaches that said crystalline semiconductor island includes carbon and nitrogen at a concentration not lower than 1×10^{16} cm^{-3}, and oxygen at a concentration not lower than 1×10^{17} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of

ordinary skill in the art to use carbon and nitrogen at a concentration not lower than 1×10^{16} cm^{-3}, and oxygen at a concentration not lower than 1×10^{17} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 116, Zhang[1] teaches in figures 1a, 1b, 2a – 2d; and column 12, lines 1 – 30 wherein said monodomain region has a grain size of 50 μm or more. It should be noted that the crystal grains (3) grown around metal portions (2) must have a grain size of 50 – 100 μm when the metal portions are set from 25 – 50 μm apart as disclosed by Zhang[1] in column 12, lines 1 – 30.

With regard to claim 123, Zhang[1] discloses in figure 4c a semiconductor device. Zhang[1] discloses in figures 1a – 1c, 2a - 2d, and 4a – 4c a crystalline semiconductor island on an insulating surface. Zhang[1] discloses in figures 4b and 4c source and drain regions in said semiconductor island. Zhang[1] discloses in figure 4b a channel forming region between said source and drain regions. Zhang[1] discloses in figures 1a- 1c, 2a – 2d, and 4a – 4c a gate insulating film adjacent to at least said channel forming region. Zhang[1] discloses in figures 1a- 1c, 2a – 2d, and 4a – 4c a gate electrode adjacent to said channel forming region having said gate insulating film therebetween, wherein said crystalline semiconductor island is formed in a monodomain region which contains no grain boundary. Zhang[1] discloses in column 9, lines 38 – 43 wherein the crystalline semiconductor island includes carbon and nitrogen at a concentration less than 1×10^{18} cm^{-3}. It is not clear if Zhang[1] teaches that said crystalline semiconductor island includes carbon and nitrogen at a concentration not higher than 5×10^{18} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use carbon and nitrogen at a concentration not higher than 5×10^{18} cm^{-3} in the device of

Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap. No

differences have been pointed out in the formation of the channel forming region of Zhang[1] and

the channel forming region of the current pending claim in view of the currently pending

specification. Therefore Zhang[1] must teach in figures 1a – 1c, 2a – 2d and 4a – 4c wherein said

semiconductor device has a S value of 0.03-0.3, because an identical S value is a property that

must be shared by products that result from two processes that are the same. Zhang[1] discloses in

figures 4c and column 11, lines 47 – 56 wherein said crystalline semiconductor island includes

hydrogen at concentration less than 1×10^{20} cm^{-3} (i.e. the known atomic density of Si is 10^{22} cm^{-3},

less than 5% of 10^{22} is less than 10^{20}). It is not clear if Zhang[1] teaches that the hydrogen

concentration is not higher than 1×10^{20} cm^{-3}. MPEP 2144.05 states that overlapping ranges are

obvious. It would have been obvious to one of ordinary skill in the art to use the hydrogen atom

concentration of not higher than 1×10^{20} cm^{-3} in the device of Zhang[1] because the current

claimed range and the disclosed range in Zhang[1] overlap. Zhang[1] discloses in column 9, lines 38

– 45 wherein the semiconductor device includes at least one selected from the group consisting

of a p-channel thin film transistor and an n-channel thin film transistor. Zhang[1] discloses in

column 9, lines 38 – 45 wherein the semiconductor device includes a p-channel thin film

transistor having a mobility in a range of 20 – 100 cm^2/Vs. Zhang[1] is silent to the fact that the

semiconductor device includes a p-channel thin film transistor having mobility in a range of 200-

400 cm^2/Vs. Mobility is a function of the purity of the single crystal (monodomain)

semiconductor. MPEP section 2144.04, VII teaches that it is obvious to one of ordinary skill in

the art to have a more purely defect free p-channel monodomain region with mobility in a range

of 200-400 cm^2/Vs in the device of Zhang[1]. This is because the prior art teaches a suitable

method for obtaining the claimed mobility, and that fact that the monodomain region of Zhang[1] has the same utility as that of the claimed invention. Zhang[1] discloses in column 9, lines 38 – 45 wherein the semiconductor device includes an n-channel thin film transistor having a mobility in a range of 30 – 150 cm^2/Vs. Zhang[1] is silent to the fact that the semiconductor device includes an n-channel thin film transistor having mobility in a range of 500-1000 cm^2/Vs. Mobility is a function of the purity of the single crystal (monodomain) semiconductor. MPEP section 2144.04, VII teaches that it is obvious to one of ordinary skill in the art to have a more purely defect free n-channel monodomain region with mobility in a range of 500-1000 cm^2/Vs in the device of Zhang[1]. This is because the prior art teaches a suitable method for obtaining the claimed mobility, and that fact that the monodomain region of Zhang[1] has the same utility as that of the claimed invention. Further, any changes in particular device concentrations or properties would have been routine experimentation for one of ordinary skill seeking to maximize device function in the device of Zhang[1].

With regard to claim 124, Zhang[1] discloses in figures 1a, 1b, and 2a; and column 6, lines 19 – 40 wherein said crystalline semiconductor island comprises a material Ni.

With regard to claim 125, Zhang[1] discloses in figures 1a, 1b, and 2a; and column 6, lines 19 – 40 a thin film transistor wherein said material is included in said semiconductor island at a concentration less than 5 x 10^{19} cm^{-3}. It is not clear if Zhang[1] teaches that the material is included in the semiconductor at a concentration not higher than 5 x 10^{19} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use the material included in the semiconductor at a concentration not higher than 5 x 10^{19} cm^{-3} in

the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 126, Zhang[1] discloses in column 4, lines 18 – 20 wherein said semiconductor island is a silicon island.

With regard to claim 127, Zhang[1] discloses in column 9, lines 38 – 43 wherein the crystalline semiconductor island includes carbon and nitrogen at a concentration less than 1×10^{18} cm^{-3}, and oxygen at a concentration less than 1×10^{18} cm^{-3}. It is not clear if Zhang[1] teaches that said crystalline semiconductor island includes carbon and nitrogen at a concentration not lower than 1×10^{16} cm^{-3}, and oxygen at a concentration not lower than 1×10^{17} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use carbon and nitrogen at a concentration not lower than 1×10^{16} cm^{-3}, and oxygen at a concentration not lower than 1×10^{17} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 128, Zhang[1] teaches in figures 1a, 1b, 2a – 2d; and column 12, lines 1 – 30 wherein said monodomain region has a grain size of 50 μm or more. It should be noted that the crystal grains (3) grown around metal portions (2) must have a grain size of 50 – 100 μm when the metal portions are set from 25 – 50 μm apart as disclosed by Zhang[1] in column 12, lines 1 – 30.

With regard to claim 129, Zhang[1] discloses in figure 4c semiconductor device. Zhang[1] discloses in figures 1a – 1c, 2a - 2d, and 4a – 4c a crystalline semiconductor island on an insulating surface. Zhang[1] discloses in figures 4b and 4c source and drain regions in said semiconductor island. Zhang[1] discloses in figure 4b a channel forming region between said

source and drain regions. Zhang[1] discloses in figures 1a- 1c, 2a – 2d, and 4a – 4c a gate

insulating film adjacent to at least said channel forming region. Zhang[1] discloses in figures 1a-

1c, 2a – 2d, and 4a – 4c a gate electrode adjacent to said channel forming region having said gate

insulating film therebetween, wherein said crystalline semiconductor island includes carbon and

nitrogen at a concentration not higher than 5 x 1018 cm-3, wherein said channel forming region

is formed in a monodomain region which contains no grain boundary. No differences have been

pointed out in the formation of the channel forming region of Zhang[1] and the channel forming

region of the current pending claim in view of the currently pending specification. Therefore

Zhang[1] must teach in figures 1a – 1c, 2a – 2d and 4a – 4c wherein said semiconductor device has

a S value of 0.03-0.3, because an identical S value is a property that must be shared by products

that result from two processes that are the same. Zhang[1] discloses in figures 4c and column11,

lines 47 – 56 wherein said crystalline semiconductor island includes hydrogen at concentration

less than 1 x 10^{20} cm^{-3} (i.e. the known atomic density of Si is 10^{22} cm^{-3}, less than 5% of 10^{22} is

less than 10^{20}). It is not clear if Zhang[1] teaches that the hydrogen concentration is not higher than

1 x 10^{20} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been

obvious to one of ordinary skill in the art to use the hydrogen atom concentration of not higher

than 1 x 10^{20} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed

range in Zhang[1] overlap. Zhang[1] discloses in column 9, lines 38 – 45 wherein the semiconductor

device includes at least one selected from the group consisting of a p-channel thin film transistor

and an n-channel thin film transistor. Zhang[1] discloses in column 9, lines 38 – 45 wherein the

semiconductor device includes a p-channel thin film transistor having a mobility in a range of 20

– 100 cm^2/Vs. Zhang[1] is silent to the fact that the semiconductor device includes a p-channel

thin film transistor having mobility in a range of 200-400 cm^2/Vs. Mobility is a function of the

purity of the single crystal (monodomain) semiconductor. MPEP section 2144.04, VII teaches

that it is obvious to one of ordinary skill in the art to have a more purely defect free p-channel

monodomain region with mobility in a range of 200-400 cm^2/Vs in the device of Zhang[1]. This is

because the prior art teaches a suitable method for obtaining the claimed mobility, and that fact

that the monodomain region of Zhang[1] has the same utility as that of the claimed invention.

Zhang[1] discloses in column 9, lines 38 – 45 wherein the semiconductor device includes an n-

channel thin film transistor having a mobility in a range of 30 – 150 cm^2/Vs. Zhang[1] is silent to

the fact that the semiconductor device includes an n-channel thin film transistor having mobility

in a range of 500-1000 cm^2/Vs. Mobility is a function of the purity of the single crystal

(monodomain) semiconductor. MPEP section 2144.04, VII teaches that it is obvious to one of

ordinary skill in the art to have a more purely defect free n-channel monodomain region with

mobility in a range of 500-1000 cm^2/Vs in the device of Zhang[1]. This is because the prior art

teaches a suitable method for obtaining the claimed mobility, and that fact that the monodomain

region of Zhang[1] has the same utility as that of the claimed invention. Further, any changes in

particular device concentrations or properties would have been routine experimentation for one

of ordinary skill seeking to maximize device function in the device of Zhang[1].

With regard to claim 130, Zhang[1] discloses in figures 1a, 1b, and 2a; and column 6, lines

19 – 40 wherein said crystalline semiconductor island comprises a material Ni.

With regard to claim 131, Zhang[1] discloses in figures 1a, 1b, and 2a; and column 6, lines

19 – 40 a thin film transistor wherein said material is included in said semiconductor island at a

concentration less than 5 x 10^{19} cm^{-3}. It is not clear if Zhang[1] teaches that the material is included

in the semiconductor at a concentration not higher than 5×10^{19} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use the material included in the semiconductor at a concentration not higher than 5×10^{19} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 132, Zhang[1] discloses in column 4, lines 18 – 20 wherein said semiconductor island is a silicon island.

With regard to claim 133, Zhang[1] discloses in column 9, lines 38 – 43 wherein the crystalline semiconductor island includes carbon and nitrogen at a concentration less than 1×10^{18} cm^{-3}, and oxygen at a concentration less than 1×10^{18} cm^{-3}. It is not clear if Zhang[1] teaches that said crystalline semiconductor island includes carbon and nitrogen at a concentration not lower than 1×10^{16} cm^{-3}, and oxygen at a concentration not lower than 1×10^{17} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use carbon and nitrogen at a concentration not lower than 1×10^{16} cm^{-3}, and oxygen at a concentration not lower than 1×10^{17} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 134, Zhang[1] teaches in figures 1a, 1b, 2a – 2d; and column 12, lines 1 – 30 wherein said monodomain region has a grain size of 50 µm or more. It should be noted that the crystal grains (3) grown around metal portions (2) must have a grain size of 50 – 100 µm when the metal portions are set from 25 – 50 µm apart as disclosed by Zhang[1] in column 12, lines 1 – 30.

With regard to claim 135, Zhang[1] discloses in column 9, lines 38 – 45 wherein each of the concentrations of carbon, nitrogen and oxygen is measured. A method of measuring does not define a patentable feature in a device claim. Therefore, measuring the concentration of carbon, nitrogen and oxygen by the well known technique of secondary ion mass spectroscopy (SIMS) does not bear any patentable weight in this device claim. Further, it would have been obvious to one of ordinary skill in the art at the time of the present invention to use the technique of SIMS to measure the concentration of carbon, nitrogen and oxygen in the device of Zhang[1] in order to understand the electrical characteristics of the device as it relates to these features. This understanding would result in better device control.

With regard to claim 136, Zhang[1] discloses in column 9, lines 38 – 45 wherein each of the concentrations of carbon, nitrogen and oxygen is measured. A method of measuring does not define a patentable feature in a device claim. Therefore, measuring the concentration of carbon, nitrogen and oxygen by the well known technique of secondary ion mass spectroscopy (SIMS) does not bear any patentable weight in this device claim. Further, it would have been obvious to one of ordinary skill in the art at the time of the present invention to use the technique of SIMS to measure the concentration of carbon, nitrogen and oxygen in the device of Zhang[1] in order to understand the electrical characteristics of the device as it relates to these features. This understanding would result in better device control.

With regard to claim 137, Zhang[1] discloses in column 9, lines 38 – 45 wherein each of the concentrations of carbon, nitrogen and oxygen is measured. A method of measuring does not define a patentable feature in a device claim. Therefore, measuring the concentration of carbon, nitrogen and oxygen by the well known technique of secondary ion mass spectroscopy

(SIMS) does not bear any patentable weight in this device claim. Further, it would have been

obvious to one of ordinary skill in the art at the time of the present invention to use the technique

of SIMS to measure the concentration of carbon, nitrogen and oxygen in the device of Zhang[1] in

order to understand the electrical characteristics of the device as it relates to these features. This

understanding would result in better device control.

With regard to claim 138, Zhang[1] discloses in column 9, lines 38 – 45 wherein each of

the concentrations of carbon, nitrogen and oxygen is measured. A method of measuring does not

define a patentable feature in a device claim. Therefore, measuring the concentration of carbon,

nitrogen and oxygen by the well known technique of secondary ion mass spectroscopy (SIMS)

does not bear any patentable weight in this device claim. Further, it would have been obvious to

one of ordinary skill in the art at the time of the present invention to use the technique of SIMS

to measure the concentration of carbon, nitrogen and oxygen in the device of Zhang[1] in order to

understand the electrical characteristics of the device as it relates to these features. This

understanding would result in better device control.

With regard to claim 139, Zhang[1] discloses in column 9, lines 38 – 45 wherein each of

the concentrations of carbon, nitrogen and oxygen is measured. A method of measuring does not

define a patentable feature in a device claim. Therefore, measuring the concentration of carbon,

nitrogen and oxygen by the well known technique of secondary ion mass spectroscopy (SIMS)

does not bear any patentable weight in this device claim. Further, it would have been obvious to

one of ordinary skill in the art at the time of the present invention to use the technique of SIMS

to measure the concentration of carbon, nitrogen and oxygen in the device of Zhang[1] in order to

understand the electrical characteristics of the device as it relates to these features. This

understanding would result in better device control.

With regard to claim 140, Zhang[1] discloses in column 9, lines 38 – 45 wherein each of

the concentrations of carbon, nitrogen and oxygen is measured. A method of measuring does not

define a patentable feature in a device claim. Therefore, measuring the concentration of carbon,

nitrogen and oxygen by the well known technique of secondary ion mass spectroscopy (SIMS)

does not bear any patentable weight in this device claim. Further, it would have been obvious to

one of ordinary skill in the art at the time of the present invention to use the technique of SIMS

to measure the concentration of carbon, nitrogen and oxygen in the device of Zhang[1] in order to

understand the electrical characteristics of the device as it relates to these features. This

understanding would result in better device control.

With regard to claim 141, Zhang[1] discloses in column 9, lines 38 – 45 wherein each of

the concentrations of carbon, nitrogen and oxygen is measured. A method of measuring does not

define a patentable feature in a device claim. Therefore, measuring the concentration of carbon,

nitrogen and oxygen by the well known technique of secondary ion mass spectroscopy (SIMS)

does not bear any patentable weight in this device claim. Further, it would have been obvious to

one of ordinary skill in the art at the time of the present invention to use the technique of SIMS

to measure the concentration of carbon, nitrogen and oxygen in the device of Zhang[1] in order to

understand the electrical characteristics of the device as it relates to these features. This

understanding would result in better device control.

With regard to claim 143, Zhang[1] discloses in column 9, lines 38 – 45 wherein each of

the concentrations of carbon, nitrogen and oxygen is measured. A method of measuring does not

define a patentable feature in a device claim. Therefore, measuring the concentration of carbon,

nitrogen and oxygen by the well known technique of secondary ion mass spectroscopy (SIMS)

does not bear any patentable weight in this device claim. Further, it would have been obvious to

one of ordinary skill in the art at the time of the present invention to use the technique of SIMS

to measure the concentration of carbon, nitrogen and oxygen in the device of Zhang[1] in order to

understand the electrical characteristics of the device as it relates to these features. This

understanding would result in better device control.

With regard to claim 144, Zhang[1] discloses in column 9, lines 38 – 45 wherein each of

the concentrations of carbon, nitrogen and oxygen is measured. A method of measuring does not

define a patentable feature in a device claim. Therefore, measuring the concentration of carbon,

nitrogen and oxygen by the well known technique of secondary ion mass spectroscopy (SIMS)

does not bear any patentable weight in this device claim. Further, it would have been obvious to

one of ordinary skill in the art at the time of the present invention to use the technique of SIMS

to measure the concentration of carbon, nitrogen and oxygen in the device of Zhang[1] in order to

understand the electrical characteristics of the device as it relates to these features. This

understanding would result in better device control.

With regard to claim 145, Zhang[1] discloses in column 9, lines 38 – 43 wherein the

crystalline semiconductor island includes carbon and nitrogen at a concentration less than 1 x

10^{18} cm^{-3}, and oxygen at a concentration less than 1 x 10^{18} cm^{-3}. It is not clear if Zhang[1] teaches

that said crystalline semiconductor island includes carbon and nitrogen at a concentration not

higher than 5 x 10^{18} cm^{-3}, and oxygen at a concentration not higher than 5 x 10^{19} cm^{-3}. MPEP

2144.05 states that overlapping ranges are obvious. It would have been obvious to one of

ordinary skill in the art to use carbon and nitrogen at a concentration not higher than 5×10^{18} cm$^-$^{3}, and oxygen at a concentration not higher than 5×10^{19} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 146, Zhang[1] discloses in column 9, lines 38 – 45 wherein the thin film transistor is an n-channel thin film transistor having a mobility in a range of 30 – 150 cm^2/Vs. Zhang[1] is silent to the fact that the semiconductor device includes an n-channel thin film transistor having mobility in a range of 500-1000 cm^2/Vs. Mobility is a function of the purity of the single crystal (monodomain) semiconductor. MPEP section 2144.04, VII teaches that it is obvious to one of ordinary skill in the art to have a more purely defect free n-channel monodomain region with mobility in a range of 500-1000 cm^2/Vs in the device of Zhang[1]. This is because the prior art teaches a suitable method for obtaining the claimed mobility, and that fact that the monodomain region of Zhang[1] has the same utility as that of the claimed invention.

With regard to claim 147, Zhang[1] discloses in column 9, lines 38 – 43 wherein the crystalline semiconductor island includes carbon and nitrogen at a concentration less than 1×10^{18} cm^{-3}, and oxygen at a concentration less than 1×10^{18} cm^{-3}. It is not clear if Zhang[1] teaches that said crystalline semiconductor island includes carbon and nitrogen at a concentration not higher than 5×10^{18} cm^{-3}, and oxygen at a concentration not higher than 5×10^{19} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use carbon and nitrogen at a concentration not higher than 5×10^{18} cm$^-$^{3}, and oxygen at a concentration not higher than 5×10^{19} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 148, Zhang[1] discloses in column 9, lines 38 – 45 wherein the thin film transistor is one of a p-channel thin film transistor having a mobility in a range of 20 – 100 cm^2/Vs. Zhang[1] is silent to the fact that the semiconductor device includes a p-channel thin film transistor having mobility in a range of 200-400 cm^2/Vs. Mobility is a function of the purity of the single crystal (monodomain) semiconductor. MPEP section 2144.04, VII teaches that it is obvious to one of ordinary skill in the art to have a more purely defect free p-channel monodomain region with mobility in a range of 200-400 cm^2/Vs in the device of Zhang[1]. This is because the prior art teaches a suitable method for obtaining the claimed mobility, and that fact that the monodomain region of Zhang[1] has the same utility as that of the claimed invention.

With regard to claim 149, Zhang[1] discloses in column 9, lines 38 – 43 wherein the crystalline semiconductor island includes carbon and nitrogen at a concentration less than 1 x 10^{18} cm^{-3}, and oxygen at a concentration less than 1 x 10^{18} cm^{-3}. It is not clear if Zhang[1] teaches that said crystalline semiconductor island includes carbon and nitrogen at a concentration not higher than 5 x 10^{18} cm^{-3}, and oxygen at a concentration not higher than 5 x 10^{19} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use carbon and nitrogen at a concentration not higher than 5 x 10^{18} cm^{-3}, and oxygen at a concentration not higher than 5 x 10^{19} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 150, Zhang[1] discloses in column 9, lines 38 – 43 wherein the crystalline semiconductor island includes carbon and nitrogen at a concentration less than 1 x 10^{18} cm^{-3}, and oxygen at a concentration less than 1 x 10^{18} cm^{-3}. It is not clear if Zhang[1] teaches that said crystalline semiconductor island includes carbon and nitrogen at a concentration not

higher than 5×10^{18} cm^{-3}, and oxygen at a concentration not higher than 5×10^{19} cm^{-3}. MPEP

2144.05 states that overlapping ranges are obvious. It would have been obvious to one of

ordinary skill in the art to use carbon and nitrogen at a concentration not higher than 5×10^{18} cm^{-}

^{3}, and oxygen at a concentration not higher than 5×10^{19} cm^{-3} in the device of Zhang[1] because

the current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 151, Zhang[1] discloses in column 9, lines 38 – 43 wherein the

crystalline semiconductor island includes carbon and nitrogen at a concentration less than $1 \times$

10^{18} cm^{-3}, and oxygen at a concentration less than 1×10^{18} cm^{-3}. It is not clear if Zhang[1] teaches

that said crystalline semiconductor island includes carbon and nitrogen at a concentration not

higher than 5×10^{18} cm^{-3}, and oxygen at a concentration not higher than 5×10^{19} cm^{-3}. MPEP

2144.05 states that overlapping ranges are obvious. It would have been obvious to one of

ordinary skill in the art to use carbon and nitrogen at a concentration not higher than 5×10^{18} cm^{-}

^{3}, and oxygen at a concentration not higher than 5×10^{19} cm^{-3} in the device of Zhang[1] because

the current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 152, Zhang[1] discloses in column 9, lines 38 – 45 wherein the

semiconductor device includes a p-channel thin film transistor having a mobility in a range of 20

– 100 cm^2/Vs. Zhang[1] is silent to the fact that the semiconductor device includes a p-channel

thin film transistor having mobility in a range of 200-400 cm^2/Vs. Mobility is a function of the

purity of the single crystal (monodomain) semiconductor. MPEP section 2144.04, VII teaches

that it is obvious to one of ordinary skill in the art to have a more purely defect free p-channel

monodomain region with mobility in a range of 200-400 cm^2/Vs in the device of Zhang[1]. This is

because the prior art teaches a suitable method for obtaining the claimed mobility, and that fact

that the monodomain region of Zhang[1] has the same utility as that of the claimed invention.

Zhang[1] discloses in column 9, lines 38 – 45 wherein the semiconductor device includes a n-

channel thin film transistor having a mobility in a range of 30 – 150 cm^2/Vs. Zhang[1] is silent to

the fact that the semiconductor device includes an n-channel thin film transistor having mobility

in a range of 500-1000 cm^2/Vs. Mobility is a function of the purity of the single crystal

(monodomain) semiconductor. MPEP section 2144.04, VII teaches that it is obvious to one of

ordinary skill in the art to have a more purely defect free n-channel monodomain region with

mobility in a range of 500-1000 cm^2/Vs in the device of Zhang[1]. This is because the prior art

teaches a suitable method for obtaining the claimed mobility, and that fact that the monodomain

region of Zhang[1] has the same utility as that of the claimed invention.

    With regard to claim 153, Zhang[1] discloses in column 9, lines 38 – 45 wherein the

semiconductor device includes a p-channel thin film transistor having a mobility in a range of 20

– 100 cm^2/Vs. Zhang[1] is silent to the fact that the semiconductor device includes a p-channel

thin film transistor having mobility in a range of 200-400 cm^2/Vs. Mobility is a function of the

purity of the single crystal (monodomain) semiconductor. MPEP section 2144.04, VII teaches

that it is obvious to one of ordinary skill in the art to have a more purely defect free p-channel

monodomain region with mobility in a range of 200-400 cm^2/Vs in the device of Zhang[1]. This is

because the prior art teaches a suitable method for obtaining the claimed mobility, and that fact

that the monodomain region of Zhang[1] has the same utility as that of the claimed invention.

Zhang[1] discloses in column 9, lines 38 – 45 wherein the semiconductor device includes a n-

channel thin film transistor having a mobility in a range of 30 – 150 cm^2/Vs. Zhang[1] is silent to

the fact that the semiconductor device includes an n-channel thin film transistor having mobility

in a range of 500-1000 cm^2/Vs. Mobility is a function of the purity of the single crystal (monodomain) semiconductor. MPEP section 2144.04, VII teaches that it is obvious to one of ordinary skill in the art to have a more purely defect free n-channel monodomain region with mobility in a range of 500-1000 cm^2/Vs in the device of Zhang[1]. This is because the prior art teaches a suitable method for obtaining the claimed mobility, and that fact that the monodomain region of Zhang[1] has the same utility as that of the claimed invention.

With regard to claim 154, Zhang[1] discloses in column 9, lines 38 – 43 wherein the crystalline semiconductor island includes carbon and nitrogen at a concentration less than 1 x 10^{18} cm^{-3}. It is not clear if Zhang[1] teaches that said crystalline semiconductor island includes carbon and nitrogen at a concentration not higher than 5 x 10^{18} cm^{-3}. MPEP 2144.05 states that overlapping ranges are obvious. It would have been obvious to one of ordinary skill in the art to use carbon and nitrogen at a concentration not higher than 5 x 10^{18} cm^{-3} in the device of Zhang[1] because the current claimed range and the disclosed range in Zhang[1] overlap.

With regard to claim 155, Zhang[1] discloses in column 9, lines 38 – 45 wherein the second thin film transistor is one of a p-channel thin film transistor having a mobility in a range of 20 – 100 cm^2/Vs. Zhang[1] is silent to the fact that the semiconductor device includes a p-channel thin film transistor having mobility in a range of 200-400 cm^2/Vs. Mobility is a function of the purity of the single crystal (monodomain) semiconductor. MPEP section 2144.04, VII teaches that it is obvious to one of ordinary skill in the art to have a more purely defect free p-channel monodomain region with mobility in a range of 200-400 cm^2/Vs in the device of Zhang[1]. This is because the prior art teaches a suitable method for obtaining the claimed mobility, and

that fact that the monodomain region of Zhang[1] has the same utility as that of the claimed

invention.

Response to Arguments

4.   Applicant's arguments filed January 24, 2005 have been fully considered but they are not

persuasive.

5.   All responses to applicant's previous arguments are hereby incorporated from all former

office actions.

6.   With regard to applicant's argument that "the crystal grains of Zhang grow radially from

the deposited metal, grain boundaries are generated along with the crystal growth as disclosed by

Ohtani, and that a channel region includes grain boundaries," it should be noted that the rejection

is not based on Ohtani. Further, Zhang clearly shows in figure 1c wherein the channel forming

region has no grain boundary. In other words, Zhang shows in figure 1c wherein the channel

forming region, under gate 7, on the islands 6, are not formed over the grain boundaries 4.

Irrespective of how Ohtani forms grain boundaries, at the time of the present invention and

Zhang one of ordinary skill would recognize only that no grain boundaries exist in the channel

forming regions in the method of Zhang. Therefore applicant's arguments are not persuasive and

the rejection is proper.

Conclusion

7.   **THIS ACTION IS MADE FINAL.** Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Paul E. Brock II whose telephone number is (571) 272-1723. The examiner can normally be reached on 8:30 AM - 5:30 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Tom Thomas can be reached on (571) 272-1664. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent

Application Information Retrieval (PAIR) system. Status information for published applications

may be obtained from either Private PAIR or Public PAIR. Status information for unpublished

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system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Paul E Brock II